

ABSTRACT

The present invention relates to a film for a circuit board characterized in that the following A layer is adjacent to the following B layer is disclosed in the present application. A circuit board excellent in adhesion strength of a conductor layer can easily be produced by
5 using this film.

A layer: a heat-resistant resin layer with a thickness of from 2 to 250 μm which layer is made of a heat-resistant resin having a glass transition point of 200°C or more or a decomposition temperature of 300°C or more, and

10 B layer: a roughenable cured resin layer with a thickness of from 5 to 20 μm which layer is made of a cured product of a thermosetting resin composition containing at least component (a) of an epoxy resin having two or more epoxy groups in a molecule and component (b) of an epoxy curing agent, the cured product being capable of roughening with an oxidizing agent.

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